Hex Schmitt Inverter

With 5 V-Tolerant Inputs

The MC74LVX14 is an advanced high speed CMOS Schmitt inverter. The inputs tolerate voltages up to 7 V, allowing the interface of 5 V systems to 3 V systems.

The MC74LVX14 is pin and functionally compatible to the MC74LVX04, but the inputs have hysteresis and, with its Schmitt trigger function, can be used as a line receiver which will receive slow input signals.

Features

- High Speed: $t_{PD} = 6.8 \text{ ns}$ (Typ) at $V_{CC} = 3.3 \text{ V}$
- Low Power Dissipation: $I_{CC} = 2 \mu A$ (Max) at $T_A = 25^{\circ}C$
- Powerdown Protection Provided on Inputs
- Balanced Propagation Delays
- Low Noise: V_{OLP} = 0.5 V (Max)
- Pin and Function Compatible with Other Standard Logic Families
- Latchup Performance Exceeds 300 mA
- ESD Performance: Human Body Model > 2000 V; Machine Model > 200 V
- These Devices are Pb-Free and are RoHS Compliant



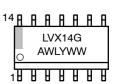
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SOIC-14 **D SUFFIX** CASE 751A



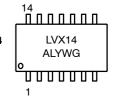


TSSOP-14 **DT SUFFIX CASE 948G**





SOEIAJ-14 **M SUFFIX CASE 965**



LVX14 = Specific Device Code = Assembly Location

= Wafer Lot WL.I = Year WW, W = Work Week G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

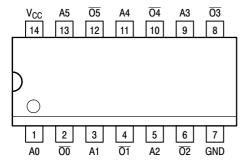


Figure 1. 14-Lead Pinout (Top View)

PIN NAMES

Pins	Function
An	Data Inputs
On	Data Outputs

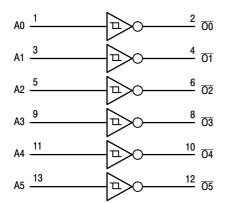


Figure 2. Logic Diagram

FUNCTION TABLE

An	On
L H	H

ORDERING INFORMATION

Device	Package	Shipping [†]
MC74LVX14DR2G	SOIC-14 (Pb-Free)	2500 Tape & Reel
MC74LVX14DTR2G	TSSOP-14*	2500 Tape & Reel
MC74LVX14MG	SOEIAJ-14 (Pb-Free)	50 Units / Rail
MC74LVX14MELG	SOEIAJ-14 (Pb-Free)	2000 Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}This package is inherently Pb-Free.

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{CC}	DC Supply Voltage	-0.5 to +7.0	V
V _{in}	DC Input Voltage	-0.5 to +7.0	V
V _{out}	DC Output Voltage	-0.5 to V $_{\rm CC}$ +0.5	V
I _{IK}	Input Diode Current	-20	mA
lok	Output Diode Current	±20	mA
l _{out}	DC Output Current, per Pin	±25	mA
Icc	DC Supply Current, V _{CC} and GND Pins	±50	mA
P_{D}	Power Dissipation	180	mW
T _{stg}	Storage Temperature	-65 to +150	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	DC Supply Voltage	2.0	3.6	V
V _{in}	DC Input Voltage	0	5.5	V
V _{out}	DC Output Voltage	0	V_{CC}	V
T_A	Operating Temperature, All Package Types	-40	+85	°C

DC ELECTRICAL CHARACTERISTICS

			v _{cc}	1	Γ _A = 25°C		$T_A = -40$	to 85°C	
Symbol	Parameter	Test Conditions	v	Min	Тур	Max	Min	Max	Unit
V _{T+}	Positive Threshold Voltage (Figure 5)		3.0			2.20		2.20	V
V _{T-}	Negative Threshold Voltage (Figure 5)		3.0	0.90			0.90		V
V _H	Hysteresis Voltage (Figure 5)		3.0	0.30		1.20	0.30	1.20	V
V _{OH}	High-Level Output Voltage (V _{in} = V _{IH} or V _{IL})	$\begin{split} I_{OH} &= -50 \; \mu\text{A} \\ I_{OH} &= -50 \; \mu\text{A} \\ I_{OH} &= -4 \; \text{mA} \end{split}$	2.0 3.0 3.0	1.9 2.9 2.58	2.0 3.0		1.9 2.9 2.48		V
V _{OL}	Low-Level Output Voltage (V _{in} = V _{IH} or V _{IL})	$I_{OL} = 50 \mu A$ $I_{OL} = 50 \mu A$ $I_{OL} = 4 \text{ mA}$	2.0 3.0 3.0		0.0 0.0	0.1 0.1 0.36		0.1 0.1 0.44	V
l _{in}	Input Leakage Current	V _{in} = 5.5 V or GND	3.6			±0.1		±1.0	μΑ
I _{CC}	Quiescent Supply Current	V _{in} = V _{CC} or GND	3.6			2.0		20.0	μΑ

AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 3.0 \text{ ns}$)

				T _A = 25°C		T _A = -40 to 85°C			
Symbol	Parameter	Test Condi	tions	Min	Тур	Max	Min	Max	Unit
t _{PLH} , t _{PHL}	Propagation Delay, Input-to-Output	V _{CC} = 2.7 V	C _L = 15 pF C _L = 50 pF		8.7 11.2	16.3 19.8	1.0 1.0	19.5 23.0	ns
		$V_{CC} = 3.3 \pm 0.3 \text{ V}$	C _L = 15 pF C _L = 50 pF		6.8 9.3	10.6 14.1	1.0 1.0	12.5 16.0	
t _{OSHL} t _{OSLH}	Output-to-Output Skew (Note 1)	$V_{CC} = 2.7 \text{ V}$ $V_{CC} = 3.3 \pm 0.3 \text{ V}$	C _L = 50 pF C _L = 50 pF			1.5 1.5		1.5 1.5	ns

Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device.
 The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}); parameter guaranteed by design.

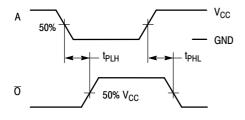
CAPACITIVE CHARACTERISTICS

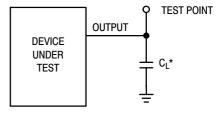
		T _A = 25°C		T _A = -40			
Symbol	Parameter	Min	Тур	Max	Min	Max	Unit
Cin	Input Capacitance		4	10		10	pF
C _{PD}	Power Dissipation Capacitance (Note 2)		21				pF

C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.
 Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}/6 (per buffer). C_{PD} is used to determine the no–load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

 $\textbf{NOISE CHARACTERISTICS} \text{ (Input } t_{r} = t_{f} = 3.0 \text{ ns, } C_{L} = 50 \text{ pF, } V_{CC} = 3.3 \text{ V, Measured in SOIC Package)}$

			T _A = 25°C		
Symbol	Characteristic	Тур	Max	Unit	
V _{OLP}	Quiet Output Maximum Dynamic V _{OL}	0.3	0.5	V	
V _{OLV}	Quiet Output Minimum Dynamic V _{OL}	-0.3	-0.5	V	
V _{IHD}	Minimum High Level Dynamic Input Voltage		2.0	V	
V _{ILD}	Maximum Low Level Dynamic Input Voltage		0.9	V	





*Includes all probe and jig capacitance

Figure 3. Switching Waveforms

Figure 4. Test Circuit

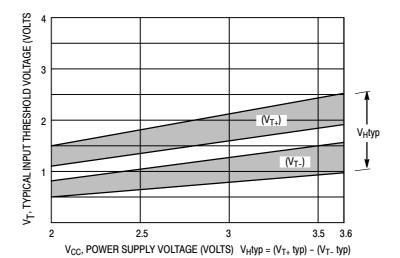
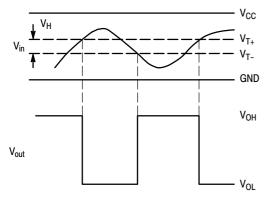
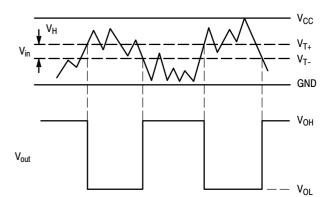


Figure 5. Typical Input Threshold, V_{T_+}, V_{T_-} versus Power Supply Voltage





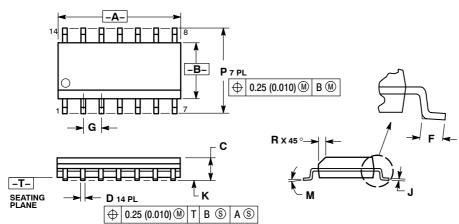
(a) A Schmitt-Trigger Squares Up Inputs With Slow Rise and Fall Times

(b) A Schmitt-Trigger Offers Maximum Noise Immunity

Figure 6. Typical Schmitt-Trigger Applications

PACKAGE DIMENSIONS

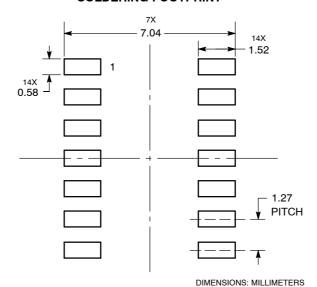
SOIC-14 **D SUFFIX** CASE 751A-03 **ISSUE J**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

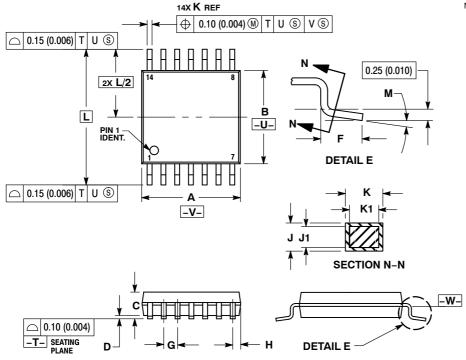
	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	8.55	8.75	0.337	0.344
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050	BSC
C	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
М	0 °	7°	0 °	7°
Р	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

SOLDERING FOOTPRINT



PACKAGE DIMENSIONS

TSSOP-14 **DT SUFFIX** CASE 948G-01 ISSUE B



- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

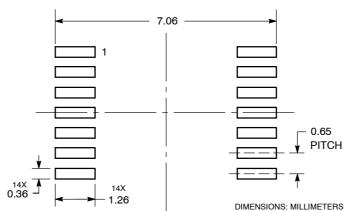
 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 - DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION.
 - INTERLEAD FLASH OR PROTRUSION.
 INTERLEAD FLASH OR PROTRUSION SHALL
 NOT EXCEED 0.25 (0.010) PER SIDE.
 5. DIMENSION K DOES NOT INCLUDE
 DAMBAR PROTRUSION. ALLOWABLE
 DAMBAR PROTRUSION SHALL BE 0.08
 (0.003) TOTAL IN EXCESS OF THE K
 DIMENSION AT MAXIMUM MATERIAL
 CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR
 REFERENCE ONLY

 - REFERENCE ONLY.
 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

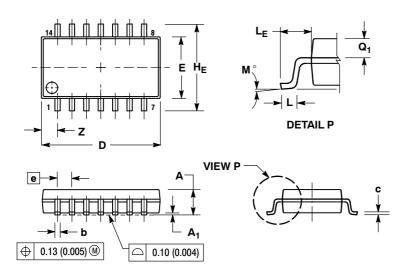
	MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	4.90	5.10	0.193	0.200	
В	4.30	4.50	0.169	0.177	
С		1.20		0.047	
D	0.05	0.15	0.002	0.006	
F	0.50	0.75	0.020	0.030	
G	0.65	BSC	0.026 BSC		
Н	0.50	0.60	0.020	0.024	
J	0.09	0.20	0.004	0.008	
J1	0.09	0.16	0.004	0.006	
Κ	0.19	0.30	0.007	0.012	
K1	0.19	0.25	0.007	0.010	
L	6.40	BSC	0.252 BSC		
М	0 °	8 °	0 °	8 °	

SOLDERING FOOTPRINT



PACKAGE DIMENSIONS

SOEIAJ-14 CASE 965-01 **ISSUE B**



NOTES:

- 1. DIMENO. Y14.5M, 1982. DIMENSIONING AND TOLERANCING PER ANSI
- CONTROLLING DIMENSION: MILLIMETER.
 DIMENSIONS D AND E DO NOT INCLUDE
- MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE, MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.

 THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH
 DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER
 RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
С	0.10	0.20	0.004	0.008
D	9.90	10.50	0.390	0.413
Е	5.10	5.45	0.201	0.215
е	1.27	BSC	0.050	BSC
HE	7.40	8.20	0.291	0.323
Ĺ	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10°
Q_1	0.70	0.90	0.028	0.035
Z		1.42		0.056

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